

Title (en)  
ELECTROPLATING IN PRESENCE OF CO<sub>2</sub>

Title (de)  
GALVANISIERUNG IN GEGENWART VON CO<sub>2</sub>

Title (fr)  
GALVANOPLASTIE EN PRESENCE DE CO<sub>2</sub>

Publication  
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Application  
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Abstract (en)  
The present invention provides a method for conducting electroplating in the presence of CO<sub>2</sub> and a metal salt-containing aqueous solution, wherein the CO<sub>2</sub> is in the form of liquid, subcritical or supercritical, the method being characterized in that a nonionic compound having a CO<sub>2</sub>-affinitive moiety is further added to the system where the aqueous solution and CO<sub>2</sub> coexist. The method of the present invention improves the efficiency of the electrochemical reaction process and enables formation of an excellent metal film.

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